

650V 4A Field Stop Trench IGBT

V _{CES}	650V
I _{C(100°C)}	4A
V _{CE(sat) (Typ.)}	1.65V
P_D	65W

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Low Switching Loss
- 3) Short Circuit Withstand Time 5µs
- 4) Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 5) Pb free Lead Plating; RoHS Compliant

Applications

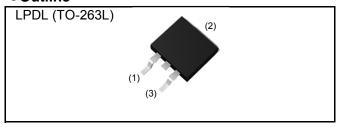
General Inverter

UPS

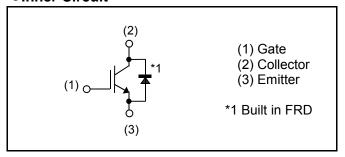
Power Conditioner

Welder

Outline



●Inner Circuit



Packaging Specifications

	Packaging	Taping
	Reel Size (mm)	330
Typo	Tape Width (mm)	24
Туре	Basic Ordering Unit (pcs)	1,000
	Packing Code	TL
	Marking	RGT8NL65D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V_{GES}	±30	V
	T _C = 25°C	I _C	8	А
Collector Current	T _C = 100°C	I _C	4	А
Pulsed Collector Current		I _{CP} *1	I _{CP} *1 12	
Diode Forward Current	T _C = 25°C	I _F	7	А
	T _C = 100°C	I _F	4	А
Diode Pulsed Forward Current		I _{FP} *1	12	А
Power Dissipation	T _C = 25°C	P _D	65	W
	T _C = 100°C	P _D	32	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax}.

●Thermal Resistance

Parameter	Symbol	Values			Unit
- Farameter		Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	2.30	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	8.70	°C/W

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_C = 10 \mu A, V_{GE} = 0 V$	650	1	-	V
Collector Cut - off Current	I _{CES}	V _{CE} = 650V, V _{GE} = 0V	1	-	10	μΑ
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$V_{CE} = 5V, I_{C} = 2.8mA$	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_C = 4A, V_{GE} = 15V$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	-	1.65 2.1	2.1 -	V

ullet IGBT Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions		Unit		
- Farameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input Capacitance	C _{ies}	V _{CE} = 30V	-	220	-	
Output Capacitance	C _{oes}	V _{GE} = 0V	-	14	-	pF
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	4.5	-	
Total Gate Charge	Qg	V _{CE} = 400V	-	13.5	-	
Gate - Emitter Charge	Q_{ge}	I _C = 4A	-	4	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	5.5	-	
Turn - on Delay Time	t _{d(on)}	I _C = 4A, V _{CC} = 400V	-	17	-	
Rise Time	t _r	$V_{GE} = 15V, R_G = 50\Omega$	-	36	-	ns
Turn - off Delay Time	t _{d(off)}	T _j = 25°C	-	69	-	
Fall Time	t _f	Inductive Load	-	71	-	
Turn - on Delay Time	t _{d(on)}	I _C = 4A, V _{CC} = 400V	-	17	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 50\Omega$	-	37	-	no
Turn - off Delay Time	t _{d(off)}	T _j = 175°C	-	86	-	ns
Fall Time	t _f	Inductive Load	-	72	-	
		I _C = 12A, V _{CC} = 520V				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 650V, V_{GE} = 15V$	FULL SQUARE			-
		$R_G = 50\Omega, T_j = 175^{\circ}C$				
		V _{CC} ≦ 360V				
Short Circuit Withstand Time	t_{sc}	V _{GE} = 15V	5	-	-	μs
		T _j = 25°C				

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Doromotor	Symbol	Conditions	Values			Lleit
Parameter			Min.	Тур.	Max.	Unit
Diode Forward Voltage	V _F	$I_F = 4A$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	-	1.45 1.4	1.9 -	V
Diode Reverse Recovery Time	t _{rr}	I _F = 4A	-	40	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	$V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	4.3	-	Α
Diode Reverse Recovery Charge	Q_{rr}		-	0.09	-	μC
Diode Reverse Recovery Time	t _{rr}	I _F = 4A	-	94	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	V _{CC} = 400V di _F /dt = 200A/μs	-	5.4	-	Α
Diode Reverse Recovery Charge	Q_{rr}	T _j = 175°C	-	0.27	-	μC

Fig.1 Power Dissipation vs. Case Temperature

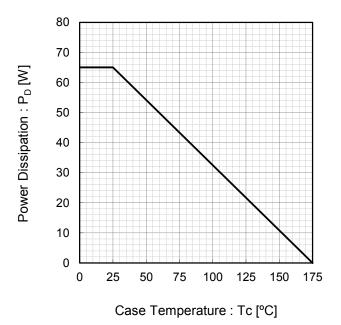


Fig.2 Collector Current vs. Case Temperature

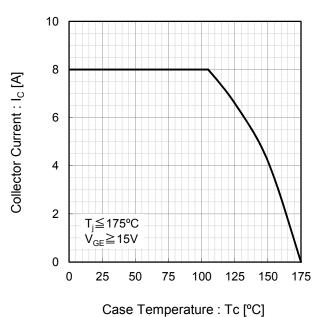


Fig.3 Forward Bias Safe Operating Area

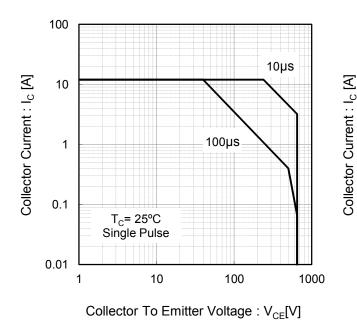


Fig.4 Reverse Bias Safe Operating Area

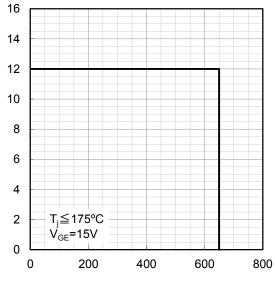


Fig.5 Typical Output Characteristics

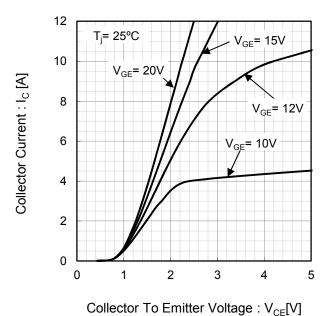
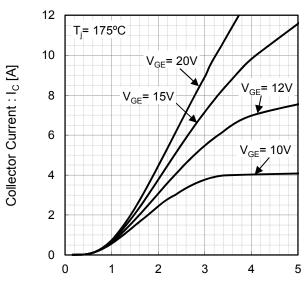


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage : $V_{CE}[V]$

Fig.7 Typical Transfer Characteristics

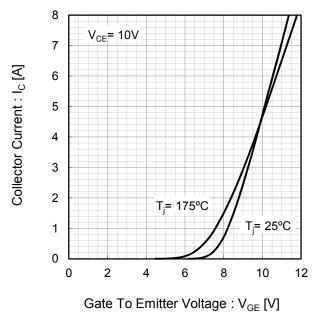


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

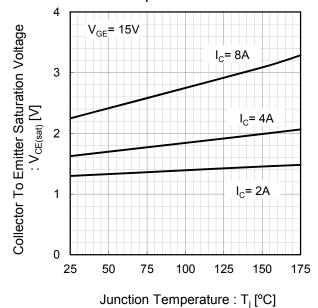
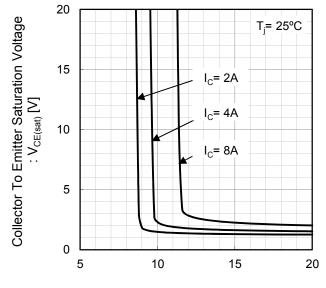
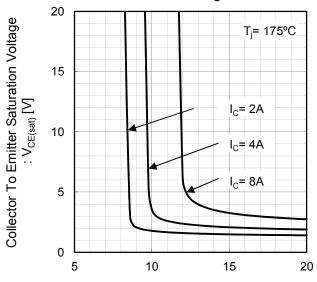


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V_{GE} [V]

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : $V_{GE}[V]$

Fig.11 Typical Switching Time vs. Collector Current

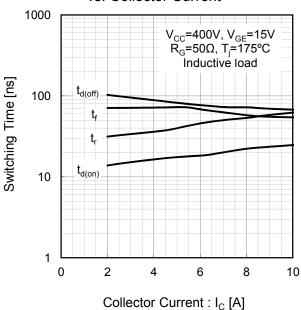
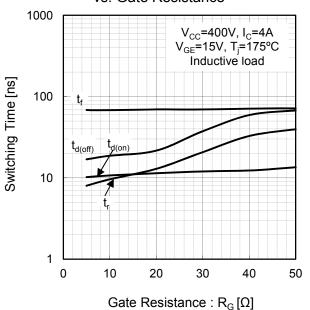


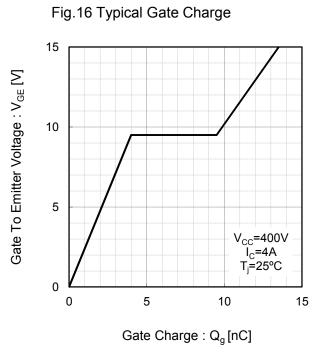
Fig.12 Typical Switching Time vs. Gate Resistance



vs. Gate Resistance 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ 0.1 V_{CC}=400V, I_C=4A V_{GE}=15V, T_i=175°C Eon Inductive load 0.01 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 1000 Capacitance [pF] Cies 100 Coes 10 f=1MHz Cres V_{GE}=0V T_i=25°C 0.1 0.01 1 10 100 Collector To Emitter Voltage : V_{CE}[V]



vs. Forward Voltage 12 10 Forward Current : I_F [A] 8 6 4 T_i= 175°C 2 T_i= 25°C 0 0.5 1.5 2 2.5 3 0

Fig.17 Typical Diode Forward Current

vs. Forward Current

120

V_{CC}=400V

di_F/dt=200A/µs

Inductive load

T_j= 175°C

T_j= 25°C

20

V_{CC}=400V

di_F/dt=200A/µs

Inductive load

T_j= 25°C

4

6

8

10

0

2

Fig.18 Typical Diode Reverse Recovery Time

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

Forward Voltage : V_F[V]

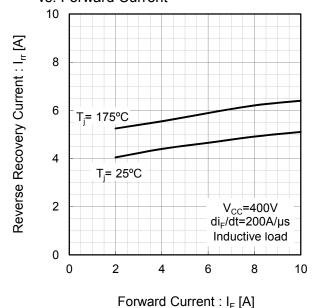


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current

Forward Current : I_F [A]

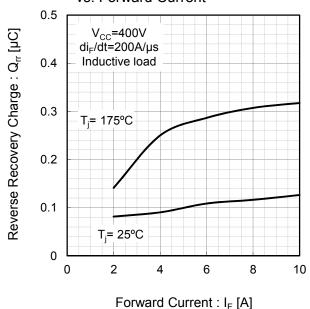
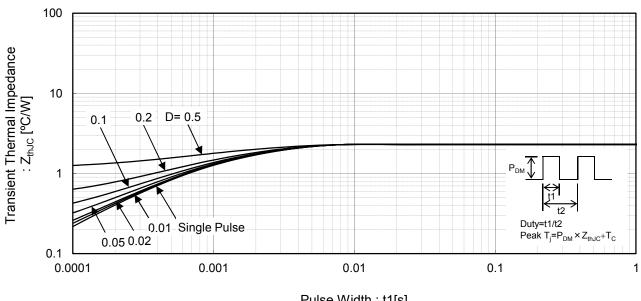
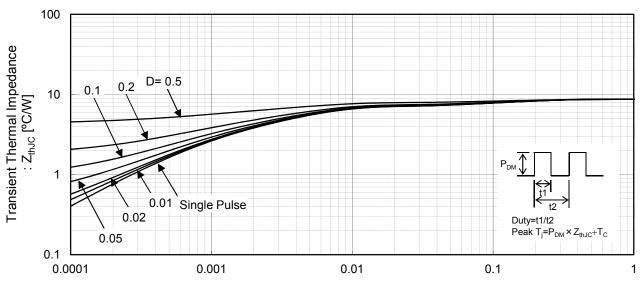


Fig.21 IGBT Transient Thermal Impedance



Pulse Width: t1[s]

Fig.22 Diode Transient Thermal Impedance



Pulse Width: t1[s]

●Inductive Load Switching Circuit and Waveform

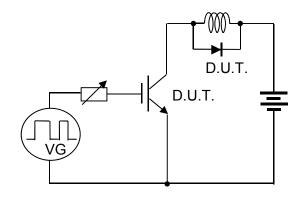


Fig.23 Inductive Load Circuit

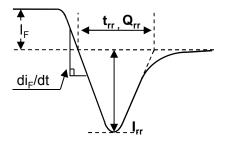


Fig.25 Diode Reverce Recovery Waveform

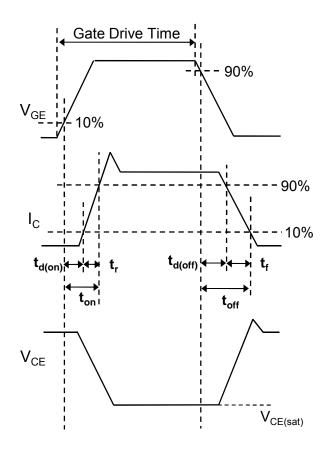


Fig.24 Inductive Load Waveform

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